XFRMR data:
Primary - Secondary Ratio 4:2.8:12 +1.15
Primary RMS Current = 5.2A
Secondary RMS Current = 0.36A
Secondary RMS = 0.17A
Primary Inductance=1.15uH

120V @ 100mA

Batting 2.74k

Two 67K resistances were put in parallel for better thermal performance during testing.

Low VIn FLyback design for Avalanche Photo Diode
You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.
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